



SPECIALTY CHEMICALS / HIGH PURITY NONIONIC CLEANER

# AmberClean™ 558W



AmberClean 558W™ is a unique, high purity blend of nonionic and amphoteric surfactants designed to remove process residues and particulate contaminants from the surfaces of sensitive microelectronic components. It is recommended for use in highly technical, aqueous cleaning processes such as those encountered in the fabrication of the most advanced read-write heads. AmberClean™ 558W contains unique dispersants and inhibitors specific to head, HSA & HGA applications. It contains very low anion and cation contaminants, and will not leave residues or films. AmberClean™ 558W is formulated to be non-aggressive toward exotic metal alloys.

## TYPICAL PHYSICAL PROPERTIES

Appearance	Clear, yellow liquid
Specific gravity, 20°C	0.988
Lbs/gallon	8.23
Surface tension @ 20°C (2% solution)	28.5 dynes/cm
pH (2% solution)	8.50
Anion content, Max. ppb (2% solution)	500 ppb
Cloud point (5% solution)	63°C
Flash point	None

## RECOMMENDED PROCESS PARAMETERS

AmberClean 558W should be diluted with deionized water to a concentration of 1.0% to 5.0%. It can be used from ambient temperature up to 60°C. In general, cleaning effectiveness doubles with every 10°C increase in temperature. AmberClean 558W can be used in immersion tanks or ultrasonic cleaning equipment.

## AVAILABLE PACKAGING

55 gallon drums, 5 gallon pails, 1 gallon containers

## Saint-Gobain Surface Conditioning

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## FEATURES AND BENEFITS

- Effectively cleans process residues and particulate contamination
- Non-aggressive towards exotic metal alloys
- Contains <500 ppb total anion and cation contaminants @ use conc.
- Will not harm sensitive microelectronic devices
- Reduces surface tension to <29 dynes/cm at 2.0%
- Nonionic-amphoteric formula will not leave films or residues
- Does not contain hazardous or volatile solvents
- Biodegradable and poses no environmental or health risks

**SURFACE CONDITIONING**

